I.   GENERAL DESCRIPTION

EM78P156E is an 8-bit microprocessor with low-power and high-speed CMOS technology. There is a 1K*13-bit Electrical One Time Programmable Read Only Memory (OTP-ROM) within it. It provides a PROTECTION bit to prevent a user's code from intruding as well as 7 OPTION bits to match the user's requirements.

Because of the OTP-ROM, the EM78P156E offers users a convenient way to develop and verify their programs. Moreover, a user's developed code can be programmed easily by an EMC writer.

II.   FEATURES

- Operating voltage range: 2.2V~5.5V
- Available in temperature range: 0°C~70°C
- Operating frequency range: DC ~ 36MHz
- Low power consumption:
    * less than 1.6 mA at 5V/4MHz
    * typical of 15 µA at 3V/32KHz
    * typical of 1 µA during the sleep mode
- 1Kx13 bits on chip ROM
- One security register to prevent the code in the OTP memory from intruding
- One configuration register to match the user's requirements
- 48x8 bits on chip registers (SRAM)
- 2 bi-directional I/O ports
- 5 level stacks for subroutine nesting
- 8-bit real time clock/counter (TCC) with selective signal sources, trigger edges, and overflow interrupt
- Two clocks per instruction cycle
- Power-down mode (SLEEP mode)
- Three available interruptions
    * TCC overflow interrupt
    * Input-port status changed interrupt (wake up from the sleep mode)
    * External interrupt
- Programmable free running watchdog timer
- 8 pull-high pins
- 7 pull-down pins
- 8 open-drain pins
- Two R-option pins
- Package type: SOP, SOIC and DIP
- 99.9% single instruction cycle commands
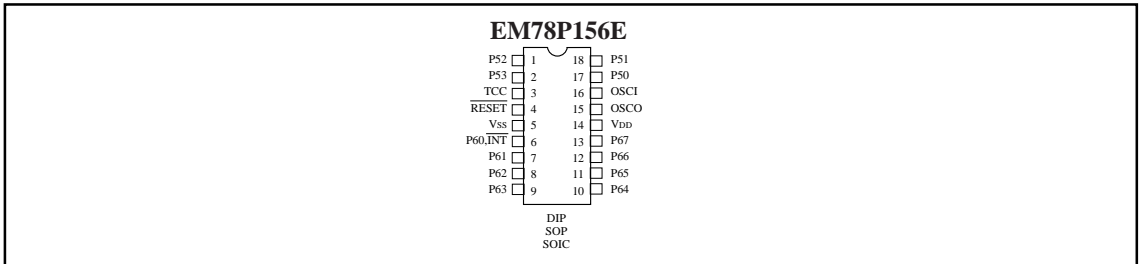
III.   PIN ASSIGNMENTS

Fig. 1   Pin assignments
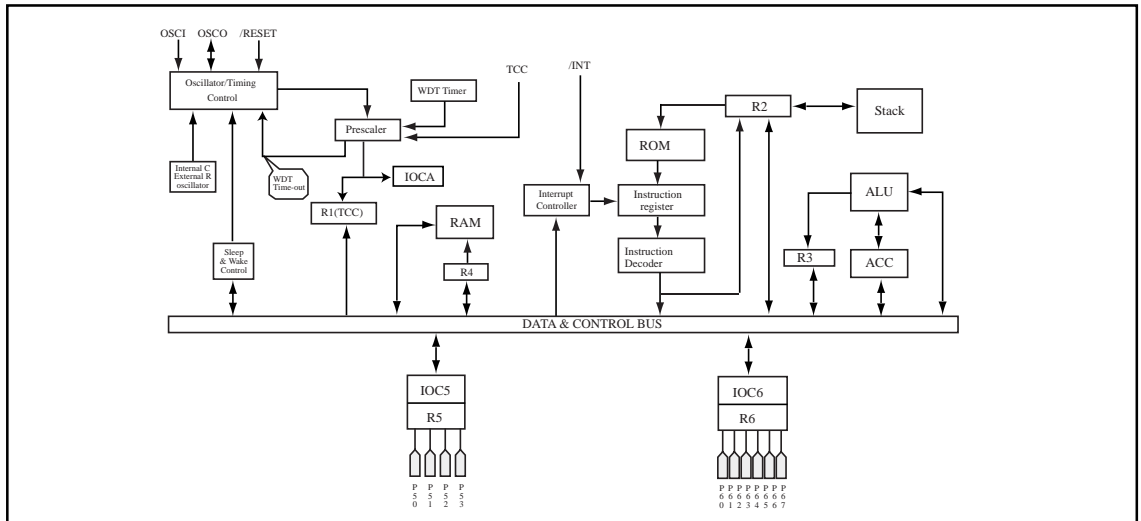
IV.   FUNCTIONAL BLOCK DIAGRAM

Fig. 2   Functional block diagram

V.   PIN DESCRIPTION

Table 1   Pin description-EM78P156E

Symbol	I/O	Function
OSCI	I	* XTAL type : Crystal input terminal or external clock input pin. * ERC type: RC oscillator input pin. * IRC type: 50K ohm pulled high for 4MHz.
OSCO	I/O	* XTAL type: Output terminal for crystal oscillator or external clock input pin. * RC type: Instruction clock ouput. * External clock signal input.
TCC	I	* Real time clock/counter with Schmitt trigger input pin, must be tied to V_{DD} or V_{SS} if not in use.

Symbol	I/O	Function
/RESET	I	* Input pin with Schmitt trigger. If this pin remains at logic low, the controller will keep in reset condition.
P50~P53	I/O	* P50~P53 are bi-directional I/O pins. P50 and P51 can also be defined as the R-option pins. P50~P52 can be pulled down by software .
P60~P67	I/O	* P60~P67 are bi-directional I/O pins. These can be pull-high or can be open-drain by software programming. In addition, P60~P63 can be pull-down also by software.
/INT	I	* External interrupt pin triggered by falling edge.
V_{DD}	-	* Power supply.
V_{SS}	-	* Ground.

VI. FUNCTION DESCRIPTION

VI.1 Operational Registers

1. **R0 (Indirect Addressing Register)**

   • R0 is not a physically implemented register. Its major function is to be an indirect addressing pointer. Any instruction using R0 as a pointer actually accesses data pointed by the RAM Select Register (R4).

2. **R1 (Time Clock /Counter)**

   • Increased by an external signal edge which is defined by TE bit (CONT-4) through the TCC pin, or by the instruction cycle clock.
   • Writable and readable as any other registers.

3. **R2 (Program Counter) & Stack**

   • R2 and hardware stacks are 10~12-bit wide. The structure is depicted in Fig. 3.
   • Generating 1024x13 bits on-chip OTP ROM addresses to the relative programming instruction codes. One program page is 1024 words long.
   • The contents of R2 are set all "0"s upon a RESET condition.
   • "JMP" instruction allows the direct loading of the lower 10 program counter bits. Thus, "JMP" allows PC to go to any location within a page.
   • "CALL" instruction loads the lower 10 bits of the PC, and then PC+1 is pushed into the stack. Thus, the subroutine entry address can locate anywhere within a page.
   " RET" ("RETL K", "RETI") instruction loads the program counter with the contents of the top-level stack.
   "ADD R2,A" allows a relative address to be added to the current PC, and the ninth and tenth bits of the PC are cleared.
   • "MOV R2,A" allows to load an address from the "A" register to the lower 8 bits of the PC, and the ninth and tenth bits of the PC are cleared.
   • Any instruction which would change the contents of R2 (e.g. "ADD R2,A", "MOV R2,A", "BC R2,6",......) will cause the ninth and tenth bits (A8~A9) of the PC to be cleared. Thus, the computed jump is limited to the first 256 locations of a page.
   • All instructions are single instruction cycle ($f$clk/2) except the instructions which would change the contents of R2 need one more instruction cycle.
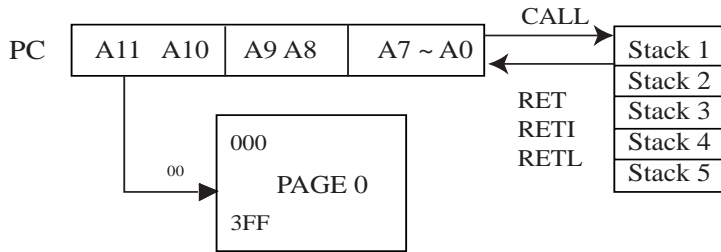
Fig. 3   Program counter organization
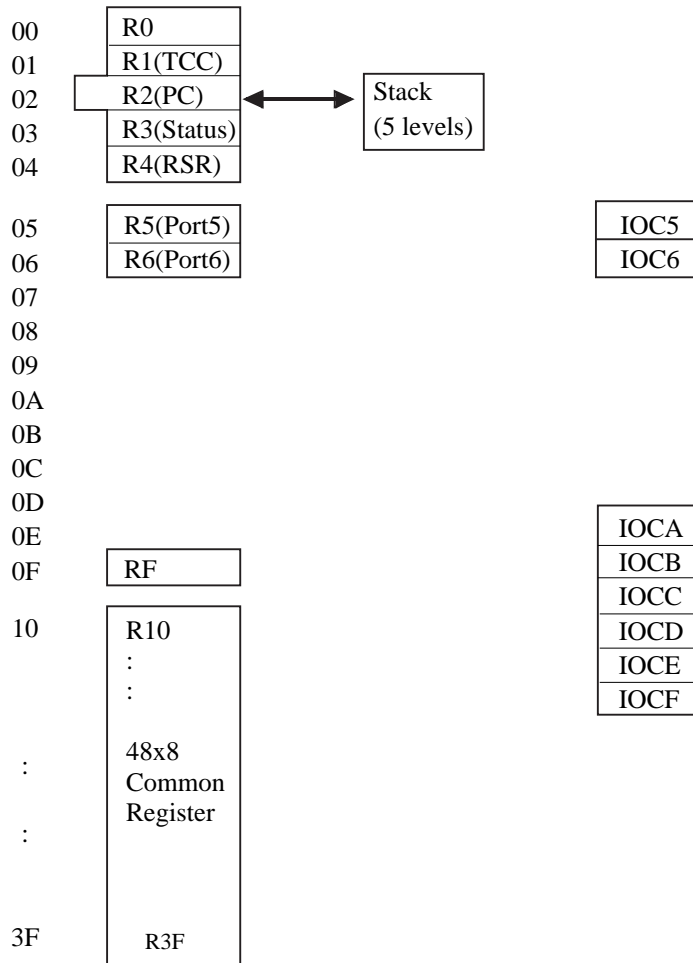
Fig. 4   Data memory configuration

4. R3 (Status Register)

7	6	5	4	3	2	1	0
GP2	GP1	GP0	T	P	Z	DC	C

- Bit 0 (C)   Carry flag
- Bit 1 (DC)   Auxiliary carry flag
- Bit 2 (Z)   Zero flag. Set to "1" if the result of an arithmetic or logic operation is zero.
- Bit 3 (P)   Power-down bit. Set to 1 during power-on or by a "WDTC" command and reset to 0 by a "SLEP" command.
- Bit 4 (T)   Time-out bit. Set to 1 by the "SLEP" and "WDTC" commands, or during power-up and reset to 0 by WDT time-out.
- Bit 5~7 (GP0~2)   General-purpose read/write bits.

5. R4 (RAM Select Register)

- Bits 0 ~ 5 are used to select registers (address: 00~06, 0F~3F) in the indirect addressing mode.
- Bits 6 ~ 7 are general-purpose read/write bits.
- See the configuration of the data memory in Fig.4.

6. R5 ~ R6 (Port 5 ~ Port 6)

- R5 and R6 are I/O registers.
- Only the lower 4 bits of R5 are available.

7. RF (Interrupt Status Register)

7	6	5	4	3	2	1	0
-	-	-	-	-	EXIF	ICIF	TCIF

- "1" means interrupt request, and "0" means non-interrupt occurence.
- Bit 0 (TCIF)   TCC overflowing interrupt flag. Set when TCC timer overflows, reset by software.
- Bit 1 (ICIF)   Port 6 input status changed interrupt flag. Set when Port 6 input changes, reset by software.
- Bit 2 (EXIF)   External interrupt flag. Set by falling edge on /INT pin, reset by software.
- Bits 3 ~ 7   Not used.
- RF can be cleared by instruction but can not be set.
- IOCF is the interrupt mask register.
- Note that the result of reading RF is the "logic AND" of RF and IOCF.

8. R10 ~ R3F

- All of these are the 8-bit general-purpose registers.

VI.2 Special Purpose Registers

1. A (Accumulator)

- Internal data transfer, or instruction operand holding
- It can not be addressed.

2. CONT (Control Register)

7	6	5	4	3	2	1	0
-	/INT	TS	TE	PAB	PSR2	PSR1	PSR0

Bit 0 (PSR0)~Bit 2 (PSR2) TCC/WDT prescaler bits.

PSR2	PSR1	PSR0	TCC Rate	WDT Rate
0	0	0	1:2	1:1
0	0	1	1:4	1:2
0	1	0	1:8	1:4
0	1	1	1:16	1:8
1	0	0	1:32	1:16
1	0	1	1:64	1:32
1	1	0	1:128	1:64
1	1	1	1:256	1:128

Bit 3 (PAB) Prescaler assignment bit.
  0: TCC
  1: WDT

Bit 4 (TE) TCC signal edge
  0: increment if the transition from high to low takes place on TCC pin
  1: increment if the transition from high to low takes place on TCC pin

Bit 5 (TS) TCC signal source
  0: internal instruction cycle clock
  1: transition on TCC pin
Bit 6 (INT) Interrupt enable flag
  0: masked by DISI or hardware interrupt
  1: enabled by ENI/RETI instruction
- CONT register is both readable and writable.

3. IOC5 ~ IOC6 (I/O Port Control Register)

- "1" puts the relative I/O pin into high impedance, while "0" defines the relative I/O pin as output.
- Only the lower 4 bits of IOC5 are able to be defined.
- IOC5 and IOC6 registers are both readable and writable.

4. IOCA (Prescaler Counter Register)

- IOCA register is readable.
- The value of IOCA is equal to the contents of Prescaler counter.
- Down counter.

5. **IOCB (Pull-down Control Register)**

7	6	5	4	3	2	1	0
/PD7	/PD6	/PD5	/PD4	-	/PD2	/PD1	/PD0

Bit 0 (/PD0)   Control bit used to enable the pull-down of P50 pin.
    0: Enable internal pull-down
    1: Disable internal pull-down
Bit 1 (/PD1)   Control bit used to enable the pull-down of P51 pin.
Bit 2 (/PD2)   Control bit used to enable the pull-down of P52 pin.
Bit 3   Not used.
Bit 4 (/PD4)   Control bit used to enable the pull-down of P60 pin.
Bit 5 (/PD5)   Control bit used to enable the pull-down of P61 pin.
Bit 6 (/PD6)   Control bit used to enable the pull-down of P62 pin.
Bit 7 (/PD7)   Control bit used to enable the pull-down of P63 pin.
- IOCB register is both readable and writable.

6. **IOCC (Open-drain Control Register)**

7	6	5	4	3	2	1	0
OD7	OD6	OD5	OD4	OD3	OD2	OD1	OD0

Bit 0 (OD0)   Control bit used to enable the open-drain of P60 pin.
    0: Disable open-drain output
    1: Enable open-drain output
Bit 1 (OD1)   Control bit used to enable the open-drain of P61 pin.
Bit 2 (OD2)   Control bit used to enable the open-drain of P62 pin.
Bit 3 (OD3)   Control bit used to enable the open-drain of P63 pin.
Bit 4 (OD4)   Control bit used to enable the open-drain of P64 pin.
Bit 5 (OD5)   Control bit used to enable the open-drain of P65 pin.
Bit 6 (OD6)   Control bit used to enable the open-drain of P66 pin.
Bit 7 (OD7)   Control bit used to enable the open-drain of P67 pin.
- IOCC register is both readable and writable.

7. **IOCD (Pull-high Control Register)**

7	6	5	4	3	2	1	0
/PH7	/PH6	/PH5	/PH4	/PH3	/PH2	/PH1	/PH0

Bit 0 (/PH0)   Control bit used to enable the pull-high of P60 pin.
    0: Enable internal pull-high
    1: Disable internal pull-high
Bit 1 (/PH1)   Control bit used to enable the pull-high of P61 pin.
Bit 2 (/PH2)   Control bit used to enable the pull-high of P62 pin.
Bit 3 (/PH3)   Control bit used to enable the pull-high of P63 pin.
Bit 4 (/PH4)   Control bit used to enable the pull-high of P64 pin.
Bit 5 (/PH5)   Control bit used to enable the pull-high of P65 pin.

Bit 6 (/PH6)   Control bit used to enable the pull-high of P66 pin.
Bit 7 (/PH7)   Control bit used to enable the pull-high of P67 pin.
• IOCD register is readable and writable.

8. IOCE (WDT Control Register)

7	6	5	4	3	2	1	0
WDTE	EIS	-	ROC	-	-	-	-

Bit 7 (WDTE)   Control bit used to enable Watchdog Timer.
   0: Disable WDT.
   1: Enable WDT.
• WDTE is both readable and writable.

Bit 6 (EIS)   Control bit used to define the function of P60 (/INT) pin.
   0: P60, bi-directional I/O pin.
   1: /INT, external interrupt pin. In this case, the I/O control bit of P60 (bit 0 of IOC6) must be set to "1".
• When EIS is "0", the path of /INT is masked. When EIS is "1", the status of /INT pin can also be read by way of reading Port 6 (R6). Refer to Fig.7(a).
• EIS is both readable and writable.

Bit 4 (ROC)   ROC is used for the R-option.
   Setting the ROC to "1" will enable the status of R-option pins (P50~P51) to be read by the controller. Clearing the ROC will disable the R-option function. If the R-option function is selected, the user must connect the P51 pin or/and P50 pin to VSS by a 430KΩ external resistor (Rex). If the Rex is connected/disconnected, the status of P50 (P51) will be read as "0"/"1". Refer to Fig.8.
• ROC is readable and writable.

Bits 0~3, 5   Not used.

9. IOCF (Interrupt Mask Register)

7	6	5	4	3	2	1	0
-	-	-	-	-	EXIE	ICIE	TCIE

Bit 0 (TCIE)   TCIF interrupt enable bit.
   0: disable TCIF interrupt
   1: enable TCIF interrupt
Bit 1 (ICIE)   ICIF interrupt enable bit.
   0: disable ICIF interrupt
   1: enable ICIF interrupt
Bit 2 (EXIE)   EXIF interrupt enable bit.
   0: disable EXIF interrupt
   1: enable EXIF interrupt
Bits 3~7   Not used.
• Individual interrupt is enabled by setting its associated control bit in the IOCF to "1".
• Global interrupt is enabled by the ENI instruction and is disabled by the DISI instruction. Refer to Fig.10.
• IOCF register is both readable and writable.

VI.3 TCC/WDT & Prescaler

There is an 8-bit counter available as prescaler for the TCC or WDT. The prescaler is available for the TCC only or the WDT only at the same time and the PAB bit of the CONT register is used to determine the prescaler assigment. The PSR0~PSR2 bits determine the ratio. The prescaler will be cleared by the instructions which write to TCC each time, when assigned to TCC mode. The WDT and prescaler, when assigned to WDT mode, will be cleared by the "WDTC" and "SLEP" instructions. Fig.5 depicts the circuit diagram of TCC/WDT.

- R1 (TCC) is an 8-bit timer/counter. The clock source of TCC can be internal clock or external clock input (edge selectable from TCC pin). If TCC signal source is from internal clock, TCC will increase by 1 in every instruction cycle (without prescaler). Refer to Fig.5, CLK=Fosc/2 or CLK=Fosc/4 is depended on the CODE option bit CLKS. CLK=Fosc/2 if CLKS bit is "0", and CLK=Fosc/4 if CLKS bit is "1". If TCC signal source is from external clock input, TCC will increase by 1 on every falling edge or rising edge of TCC pin.

- The watchdog timer is a free running on-chip RC oscillator. The WDT will keep running even the oscillator driver has been turned off (i.e. in sleep mode). During the normal operation or the sleep mode, a WDT time-out (if enabled) will cause the device to reset. The WDT can be enabled or disabled at any time during the normal mode by software programming. Refer to WDTE bit of IOCE register. With no presacler, the WDT time-out period is approximately 18 ms.
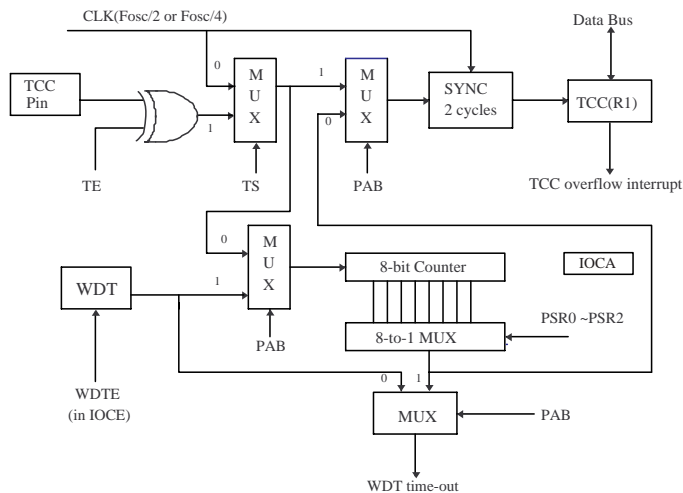

Fig. 5   Block diagram of TCC and WDT

VI.4 I/O Ports

The I/O registers, both Port 5 and Port 6, are bi-directional tri-state I/O ports. Port 6 can be pulled high internally by software. In addition, Port 6 can also have open-drain output by software. There is an input status changed interrupt (or wake-up) function on Port 6. P50 ~ P52 and P60 ~ P63 pins can be pulled down by software. Each I/O pin can be defined as "input" or "output" pin by the I/O control registers (IOC5 ~ IOC6). P50~P51 are the R-option pins enabled by setting the ROC bit in the IOCE register to 1. While the R-option function is used, P50~P51 are recommended to be used as output pins. During the period of R-option being enabled, P50~P51 must be programmed as input pins. In the R-option mode, the current consuming by the Rex should be taken into the consideration, if the low power consumption is concerned.

The I/O registers and I/O control registers are both readable and writable. The I/O interface circuits for Port 5 and Port 6 are shown in Fig.6 and Fig.7(a), 7(b) respectively.
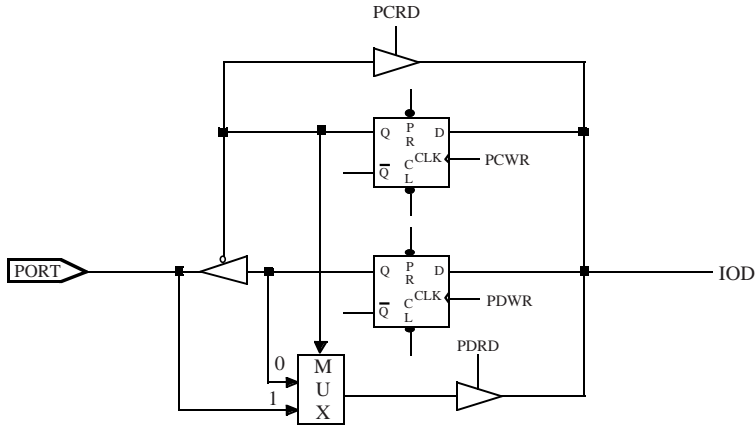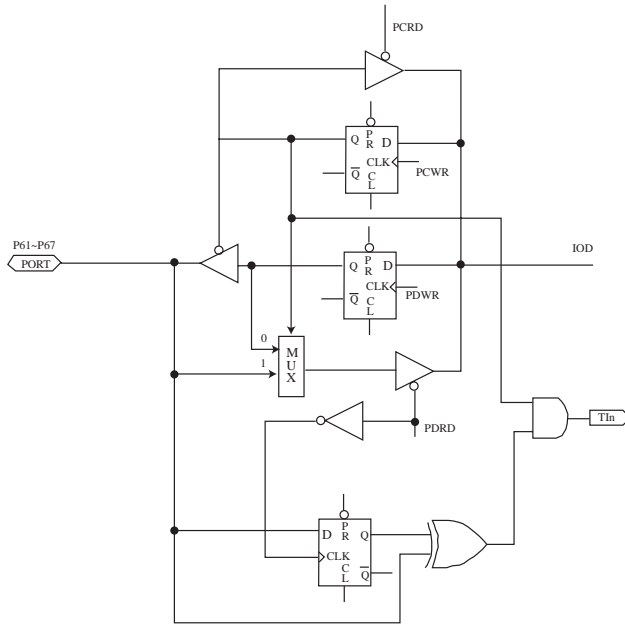

*Pull-down is not shown in the figure.

Fig. 6   The circuit of I/O port and I/O control register for Port 5
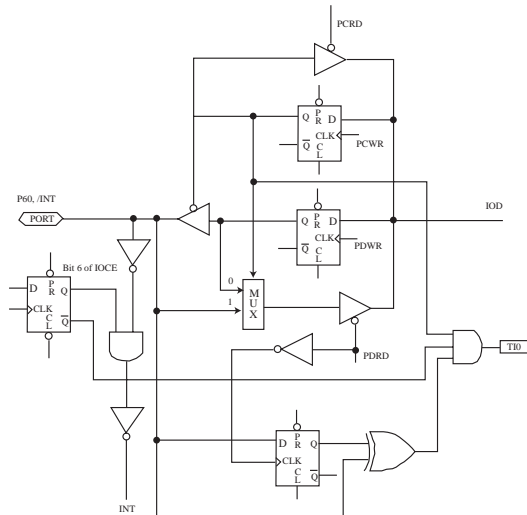
*Pull-high (down) and open-drain are not shown in the figure.

Fig. 7(a)   The circuit of I/O port and I/O control register for P60(/INT)

*Pull-high (down) and open-drain are not shown in the figure.

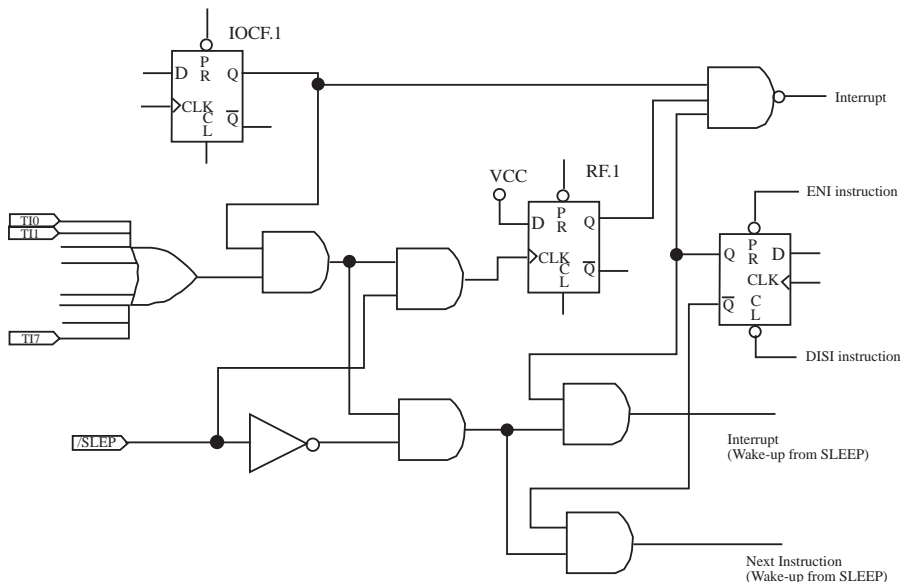Fig. 7(b)   The circuit of I/O port and I/O control register for P61~P67

Fig. 7(c)   Block diagram of I/O Port 6 with input changed interrupt/wake-up

Table 2   Usage of Port 6 input changed wake-up/interrupt function

Usage of Port 6 Input Status Changed Wake-up/Interrupt	
(I) Wake-up from Port 6 input status changed	(II) Port 6 input status changed Interrupt
(a) Before SLEEP	1. Read I/O Port 6 (MOV R6,R6)
1. Disable WDT[1] (using very carefully)	2. Execute "ENI"
2. Read I/O Port 6 (MOV R6,R6)	3. Enable interrupt (Set IOCF.1)
3. Execute "ENI" or "DISI"	4. If Port 6 changed (interrupt)
4. Enable interrupt (Set IOCF.1)	$\rightarrow$ Interrupt vector (008H)
5. Execute "SLEP" instruction	
(b) After wake-up	
1. If "ENI" $\rightarrow$ Interrupt vector (008H)	
2. If "DISI" $\rightarrow$ Next instruction	

[1]   Note : Software disables WDT (watchdog timer) but hardware must be enabled before using port6 changed
wake-up function. (CODE Option Register, bit 11 (ENWDTB-) set to "1").
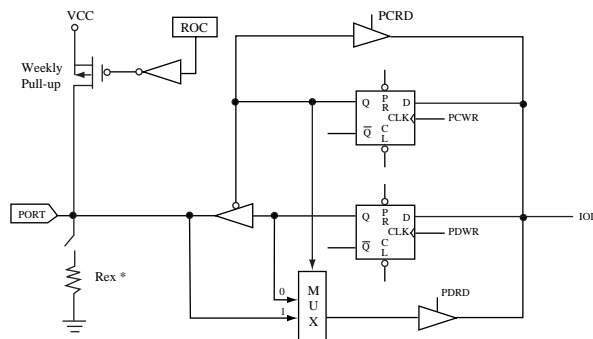
* The Rex is 430K ohm external resistor.

Fig. 8   The circuit of I/O port with R-option (P50,P51)

VI.5   RESET and Wake-up

1.   RESET

The RESET can be caused by
(1)   Power-on reset
(2)   /RESET pin input "low", or
(3)   WDT time-out (if enabled).

Note that only power-on reset, or only voltage detector in Case (1) is enabled in the system by CODE option bit.
Refer to Fig. 9. The device will be kept in a RESET condition for a period of approx. 18ms (one-oscillator start-up timer period) after the reset is detected. Once the RESET occurs, the following functions
are performed.
• The oscillator is running, or will be started.
• The Program Counter (R2) is set to all "0".
• All I/O port pins are configured as input mode (high-impedance state).

- The Watchdog Timer and prescaler are cleared.
- Upon power-on, the upper 3 bits of R3 are cleared.
- The bits of the CONT register are set to all "1" except the bit 6 (INT flag).
- The bits of the IOCA register are set to all "1".
- The bits of the IOCB register are set to all "1".
- The IOCC register is cleared.
- The bits of the IOCD register are set to all "1".
- Bit 7 of the IOCE register is set to "1", and Bits 4 and 6 are cleared.
- Bits 0~2 of RF register and bits 0~2 of IOCF register are cleared.

Executing the "SLEP" instruction can perform the sleep mode (power-down mode). While entering sleep mode, WDT (if enabled) is cleared but keeps running. The controller can be awakened by
(1) external reset input on /RESET pin,
(2) WDT time-out (if enabled), or
(3) Port 6 input status changed (if enabled).

The first two cases will cause the EM78P156E to reset. The T and P flags of R3 can be used to determine the source of the reset (wake-up). The last case is considered the continuation of program execution and the global interrupt ("ENI" or "DISI" being executed) decides whether or not the controller branches to the interrupt vector following wake-up. If ENI is executed before SLEP, the instruction will begin to execute from the address 008H after wake-up. If DISI is executed before SLEP, the instruction will restart from the place where is right next to SLEP after wake-up.

Only one of the cases 2 and 3 can be enabled before entering the sleep mode. That is,
[a] if Port 6 input status changed interrupt is enabled before SLEP , WDT must be disabled by software; however, the WDT bit in the option register is still enabled. Hence, the EM78P156E can be awakened only by case 1 or 3.
[b] if WDT is enabled before SLEP, Port 6 input status changed interrupt must be disabled. Hence, the EM78P156E can be awakened only by case 1 or 2. Refer to the section on interrupt.

If Port 6 input status changed interrupt is used to wake up the EM78P156E (the case [a]), the following instructions must be executed before SLEP:

```
MOV A, 0bxx000110        ; Select internal TCC clock
CONTW
CLR R1                   ; Clear TCC and prescaler
MOV A, 0bxxxx1110        ; Select WDT prescaler
CONTW
WDTC                     ; Clear WDT and prescaler
MOV A, 0b0xxxxxxx        ; Disable WDT
IOW RE
MOV R6, R6               ; Read Port 6
MOV A, 0b00000x1x        ; Enable Port 6 input changed interrupt
IOW RF
ENI (or DISI)            ; Enable (or disable) global interrupt
SLEP        ; Sleep
NOP
```

One problem should be aware that after waking up from the sleep mode, WDT would enable automatically. The WDT operation (being enabled or disabled) should be handled appropriately by software after waking up from the sleep mode.

Table 3   The summary of the initialized values for registers

Address	Name	Reset Type	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
N/A	IOC5	Bit Name	X	X	X	X	C53	C52	C51	C50
		Power-on	U	U	U	U	1	1	1	1
		/RESET and WDT	U	U	U	U	1	1	1	1
		Wake-up from Pin Changed	U	U	U	U	P	P	P	P
N/A	IOC6	Bit Name	C67	C66	C65	C64	C63	C62	C61	C60
		Power-on	1	1	1	1	1	1	1	1
		/RESET and WDT	1	1	1	1	1	1	1	1
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
N/A	CONT	Bit Name	X	/INT	TS	TE	PAB	PSR2	PSR1	PSR0
		Power-on	1	0	1	1	1	1	1	1
		/RESET and WDT	1	0	1	1	1	1	1	1
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
0X00	R0(IAR)	Bit Name	-	-	-	-	-	-	-	-
		Power-on	U	U	U	U	U	U	U	U
		/RESET and WDT	P	P	P	P	P	P	P	P
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
0X01	R1(TCC)	Bit Name	-	-	-	-	-	-	-	-
		Power-on	0	0	0	0	0	0	0	0
		/RESET and WDT	0	0	0	0	0	0	0	0
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
0X02	R2(PC)	Bit Name	-	-	-	-	-	-	-	-
		Power-on	0	0	0	0	0	0	0	0
		/RESET and WDT	0	0	0	0	0	0	0	0
		Wake-up from Pin Changed	**0/P	**0/P	**0/P	**0/P	**1/P	**0/P	**0/P	**0/P
0X03	R3(SR)	Bit Name	GP2	GP1	GP0	T	P	Z	DC	C
		Power-on	0	0	0	1	1	U	U	U
		/RESET and WDT	0	0	0	T	T	P	P	P
		Wake-up from Pin Changed	P	P	P	T	T	P	P	P
0x04	R4(RSR)	Bit Name	GP1	GP0	-	-	-	-	-	-
		Power-on	1	1	U	U	U	U	U	U
		/RESET and WDT	1	1	P	P	P	P	P	P
		Wake-up from Pin Changed	1	1	P	P	P	P	P	P
0x05	R5(P5)	Bit Name	X	X	X	X	P53	P52	P51	P50
		Power-on	0	0	0	0	U	U	U	U
		/RESET and WDT	0	0	0	0	P	P	P	P
		Wake-up from Pin Changed	0	0	0	0	P	P	P	P
0x06	R6(P6)	Bit Name	P67	P66	P65	P64	P63	P62	P61	P60
		Power-on	U	U	U	U	U	U	U	U
		/RESET and WDT	P	P	P	P	P	P	P	P
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
0x0F	RF(ISR)	Bit Name	X	X	X	X	X	EXIF	ICIF	TCIF
		Power-on	U	U	U	U	U	0	0	0
		/RESET and WDT	U	U	U	U	U	0	0	0
		Wake-up from Pin Changed	U	U	U	U	U	P	P	P
0x0A	IOCA	Bit Name	-	-	-	-	-	-	-	-
		Power-on	1	1	1	1	1	1	1	1
		/RESET and WDT	1	1	1	1	1	1	1	1
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P

Address	Name	Reset Type	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x0B	IOCB	Bit Name	/PD7	/PD6	/PD5	/PD4	X	/PD2	/PD1	/PD0
		Power-on	1	1	1	1	U	1	1	1
		/RESET and WDT	1	1	1	1	U	1	1	1
		Wake-up from Pin Changed	P	P	P	P	U	P	P	P
0x0C	IOCC	Bit Name	OD7	OD6	OD5	OD4	OD3	OD2	OD1	OD0
		Power-on	0	0	0	0	0	0	0	0
		/RESET and WDT	0	0	0	0	0	0	0	0
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
0x0D	IOCD	Bit Name	/PH7	/PH6	/PH5	/PH4	/PH3	/PH2	/PH1	/PH0
		Power-on	1	1	1	1	1	1	1	1
		/RESET and WDT	1	1	1	1	1	1	1	1
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P
0x0E	IOCE	Bit Name	WDTC	EIS	X	ROC	X	X	X	X
		Power-on	1	0	U	0	U	U	U	U
		/RESET and WDT	1	0	U	0	U	U	U	U
		Wake-up from Pin Changed	1	P	U	P	U	U	U	U
0x0F	IOCF	Bit Name	X	X	X	X	X	EXIE	ICIE	TCIE
		Power-on	U	U	U	U	U	0	0	0
		/RESET and WDT	U	U	U	U	U	0	0	0
		Wake-up from Pin Changed	U	U	U	U	U	P	P	P
0x10 ~ 0x3F	R10~R3F	Bit Name	-	-	-	-	-	-	-	-
		Power-on	U	U	U	U	U	U	U	U
		/RESET and WDT	P	P	P	P	P	P	P	P
		Wake-up from Pin Changed	P	P	P	P	P	P	P	P

** To jump address 0x08, or to execute the instruction which is next to the "SLEP" instruction.
X: not used.   U: unknown or don't care.   P: previous value before reset.
t: check Table 4

2.   The status of T and P of STATUS register

A RESET condition can be caused by the following events:
1. a power-on condition,
2. a high-low-high pulse on /RESET pin, and
3. Watchdog Timer time-out.

The values of T and P, listed in Table 4 can be used to check how the processor wakes up. Table 5 shows the events which may affect the status of T and P .

Table 4   The values of T and P after RESET

Reset Type	T	P
Power-on	1	1
/RESET during operating mode	*P	*P
/RESET wake-up during SLEEP mode	1	0
WDT during operating mode	0	P
WDT wake-up during SLEEP mode	0	0
Wake-up on pin changed during SLEEP mode	1	0

*P: Previous status before reset

Table 5 The status of T and P being affected by events

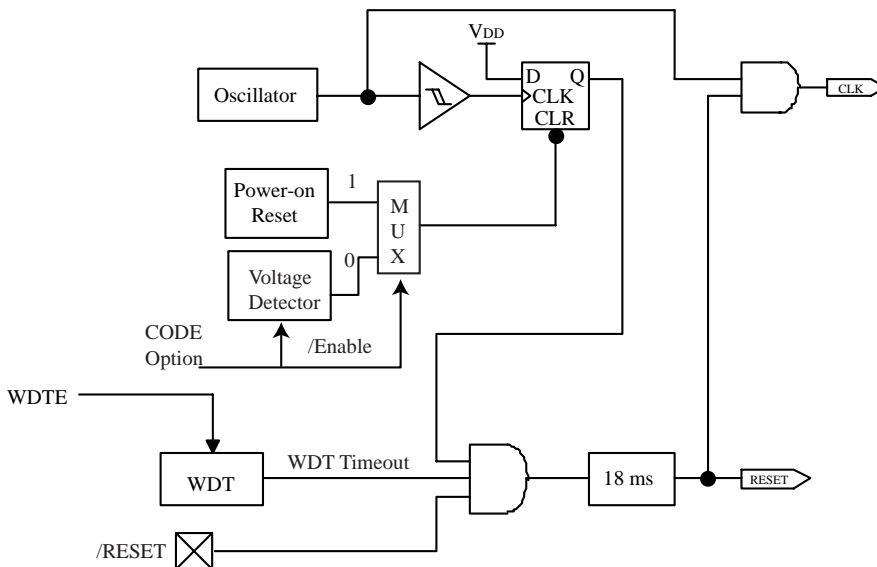| Event	T	P
Power-on	1	1
WDTC instruction	1	1
WDT time-out	0	*P
SLEP instruction	1	0
Wake-up on pin changed during SLEEP mode	1	0

*P: Previous value before reset

Fig. 9 Block diagram of Reset of controller

VI.6 Interrupt

EM78P156E has three falling edge interrupts listed below :
(1) TCC overflow interrupt
(2) Port 6 input status changed interrupt
(3) External interrupt [(P60//INT) pin].

Before Port 6 input status changed interrupt being enabled, reading Port 6 (e.g. "MOV R6,R6") is necessary.
Each pin of Port 6 can have this feature if its status changed. Any pin configured as output or P60 pin configured
as /INT is excluded from this function. The Port 6 input status changed interrupt can wake up the EM78P156E from the
sleep mode if it is enabled prior to going into the sleep mode by executing SLEP. When waking up, the controller will
continue to execute the succesive address if the global interrupt is disabled or branch to the interrupt vector 008H if the
global interrupt is enabled.

RF is the interrupt status register, which records the interrupt requests in the relative flags/bits. IOCF is an
interrupt mask register. The global interrupt is enabled by the ENI instruction and is disabled by the DISI
instruction. When one of the interrupts (when enabled) occurs, the next instruction will be fetched from address

008H. Once in the interrupt service routine, the source of an interrupt can be determined by polling the flag bits in RF. The interrupt flag bit must be cleared by instructions before leaving the interrupt service routine and enabling interrupts to avoid recursive interrupts.

The flag (except ICIF bit) in the Interrupt Status Register (RF) is set regardless of the status of its mask bit or the execution of ENI. Note that the outcome of RF will be the logic AND of RF and IOCF. Refer to Fig.10. The RETI instruction ends the interrupt routine and enables the global interrupt (the execution of ENI).

When an interrupt is generated by the INT instruction (when enabled), the next instruction will be fetched from address 001H
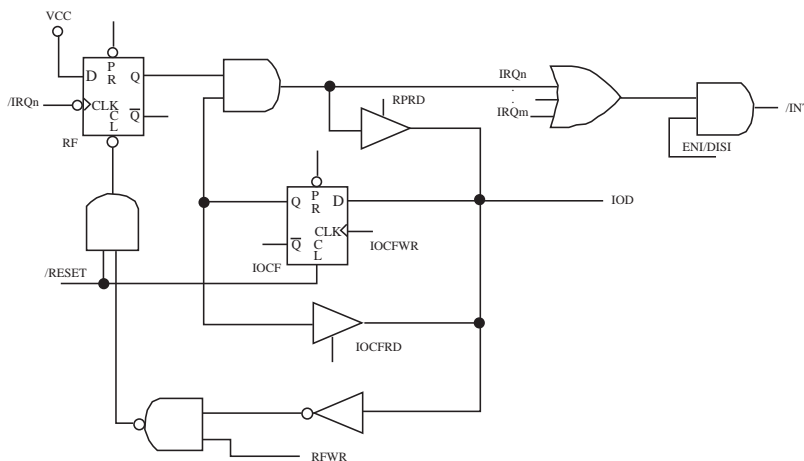

Fig. 10   Interrupt input circuit

VI.7 Oscillator

1. Oscillator Modes

EM78P156E can be operated in four different oscillator modes. There are Internal Capacitor oscillator mode (IRC), External RC oscillator mode (ERC), High XTAL oscillator mode (HXT) and Low XTAL oscillator mode (LXT). Users can select one of them by programming MS and HLF in the CODE option register. Table 6 depicts how these four modes to be defined.

The up-limited operation frequency of crystal/resonator on the different VDDs is listed in Table 7.

Table 6   Oscillator Modes defined by MS, HLF, HLP and IRCEN

Mode	MS	HLF	HLP	IRCEN
External RC oscillator mode	0	*X	*X	1
High XTAL oscillator mode	1	1	*X	*X
Low XTAL oscillator mode	1	0	0	*X
Internal C, External R oscillator mode	0	*X	*X	0

<Note>   1. X, Do not care
2. The transient point of system frequency between HXT and LXY is around 400 KHz.

Table 7 The summary of maximum operating speeds

Conditions	VDD (V)	Fxt max. (MHz)
Two clocks	2.5	8
	3	12
	5	18
	6.4	20
Four clocks	2.5	16
	3	24
	5	36
	6.5	40

2. Crystal Oscillator/Ceramic Resonators (XTAL)

EM78P156E can be driven by an external clock signal through the OSCI pin as shown in Fig.11
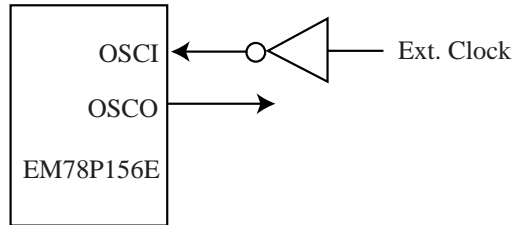

Fig. 11   Circuit for External Clock Input

In the most applications, pin OSCI and pin OSCO can be connected with a crystal or ceramic resonator to generate oscillation. Fig.12 depicts the circuit. It is the same no matter in the HXT mode or in the LXT mode. Table 8 recommends the values of C1 and C2. Since each resonator has its own attribute, users should refer to their specifications for appropriate values of C1 and C2. RS, a serial resistor, may be necessary for AT strip cut crystal or low frequency mode
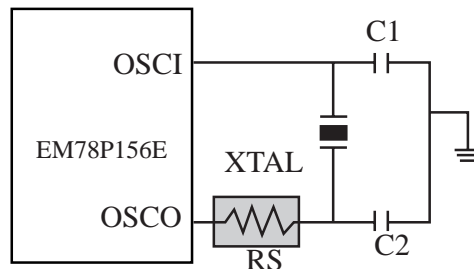

Fig. 12   Circuit for Crystal/Resonator

Table 8 Capacitor Selection Guide for Crystal Oscillator or Ceramic Resonators

Oscillator Type	Frequency Mode	Frequency	C1 (pF)	C2 (pF)
Ceramic Resonator	HXT	455 KHz	100~150	100~150
		1.00 MHz	40~80	40~80
		2.0 MHz	20~40	20~40
		4.0 MHz	10~30	10~30
Crystal Oscillator	LXT	32.768 KHz	25	15
		100 KHz	25	25
		200 KHz	25	25
	HXT	455 KHz	20~40	20~150
		1.0 MHz	15~30	15~30
		2.0 MHz	15	15
		4.0 MHz	15	15

3. **ERC Oscillator Mode**

For some applications whose timing need not be calculated precisely, the RC oscillator (Fig.13) offers a lot of cost savings. Nevertheless, it should be aware that the frequency of the RC oscillator is the function of the supply voltage, the values of the resistor (Rext), the capacitor (Cext), and even the operation temperature.
Moreover to this, the frequency also changes slightly from one chip to another due to the process variation.

In order to maintain a stable system frequency, the values of the Cext should not be less than 20pF as well as the value of Rext should not be greater than 1M ohm. If they can not be kept in this range, the frequency is affected easily by noise, humidity and leakage.

The smaller Rext the RC oscillator has, the faster frequency it gets. On the contrary, for very low Rext values, for instance, 1KΩ, the oscillator becomes unstable because the NMOS can not discharge the current of the capacitance correctly.

On a basis of the above reasons, it must be kept in mind that all of the supply voltage, the operation temperature, the components of the RC oscillator, the package types and the ways of PCB layout will effect the system frequency.
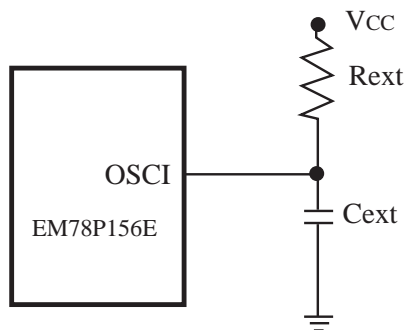

Fig. 13 Circuit for External RC Oscillator Mode

Table 9   RC Oscillator Frequencies

Cext	Rext	Average Fosc @ 5V, 25°C	Average Fosc @ 3V, 25°C
20pF	3.3k	3.92 MHz	3.65 MHz
	5.1k	2.67 MHz	2.60 MHz
	10k	1.39 MHz	1.40 MHz
	100k	1.49 KHz	156 KHz
100pF	3.3k	1.39 MHz	1.33 MHz
	5.1k	940 KHz	920 KHz
	10k	480 KHz	475 KHz
	100k	52 KHz	50 KHz
300pF	3.3k	595 KHz	560 KHz
	5.1k	400 KHz	390 KHz
	10k	200 KHz	200 KHz
	100k	21 KHz	20 KHz

* 1. Measured on DIP packages.

2. Design reference only

4.   IRC Oscillator Mode

In IRC mode, it consists of an internal C which default frequency value is 4MHz. We suggest that the external Resistant value here should be 50KΩ connected to vdd with internal C.

VI.8   CODE Option Register

1.   Code Option Register

The EM78P156E has one Code option register which is not a part of the normal program memory. The option bits can not be accessed during normal program execution.

12	11	10	9	8	7	6	5~0
MS	ENWDTB	CLKS	PTB	HLF	IRCEN	HLP	------

Bit 12 (MS): Oscillator type selection.

   0: RC type

   1: XTAL type (XTAL1 and XTAL2)

Bit 11 (ENWDTB): Watchdog Timer enable.

   0: Enable

   1: Disable

Bit 10 (CLKS): Instruction period option.

   0: two oscillator periods

   1: four oscillator periods

   Refer to the section of Instruction Set.

Bit 9 (PTB): Protect bit

   0: Enable

   1: Disable

Bit 8 (HLF): XTAL frequency selection.

   0: XTAL2 type (Low frequency, 32.768KHz)

1: XTAL1 type (High frequency)

This bit will affect system oscillation only when Bit 12 (MS) is "1". When MS is "0", HLF must be "0".

Bit 7 (IRCEN): RC oscillator selection.

   0: R connected to Vdd with internal C.

   1: External RC
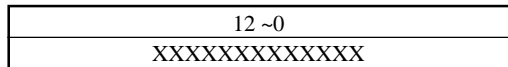
Bit 6 (HLP): Power selection.

   0: Low power

   1: High power

Bits 5 ~ 0: Not used.

2.   **User's ID Register**

The EM78P156E has one User's ID register which is not a part of the normal program memory. The User's ID bits can not be accessed during normal program execution.

12 ~0
XXXXXXXXXXXXX

Bit 12 ~ 0: User's ID code.

VI.9   Power-on Considerations

Any microcontroller is not warranted to start proper operation before the power supply stays in its steady state. EM78P156E is equipped with Power On Voltage Detector (POVD) which the detective level is about 1.8V. It will work well if Vdd rises quickly enough (50ms or less). In many critical applications; however, extra devices are still required to assist in solving power-up problems.

VI.10   External Power-on Reset Circuit

The circuit shown in Fig.14 implements an external RC to produce the reset pulse. The pulse width (time constant) should keep long enough until Vdd has reached minimum operation voltage. This circuit is used when the power supply has slow rise time. Because the current leakage from the /RESET pin is about 5A, it is recommended that R should not be greater than 40K. In this way, the voltage in pin /RESET will be held below 0.2V. The diode (D) acts a short circuit at the moment of power-down. The capacitor, C, will be discharged rapidly and fully. Rin, the current-limited resistor, protects against a high discharging current or ESD (electrostatic discharge) flowing to pin /RESET.
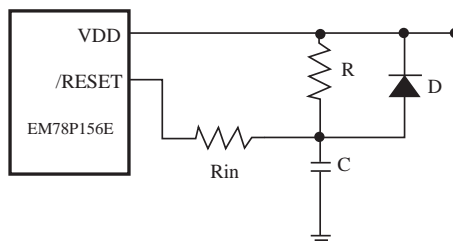

Fig. 14   External Power-up Reset Circuit

VI.11 Residue Voltage Protection

In some applications, replacing battery as an instance, device power (Vdd) is taken off and recovered within a few seconds. A residue voltage, which trips below Vdd min but not to zero, may exist. This condition may cause a poor power-on reset. Fig.15 and Fig.16 show how to build the residue voltage protection circuit
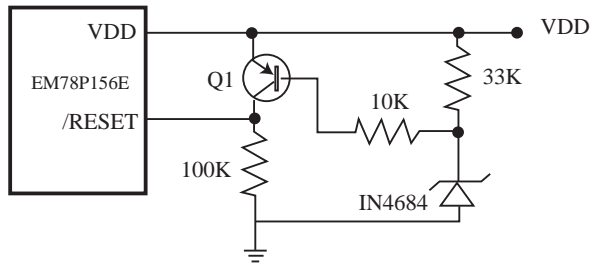

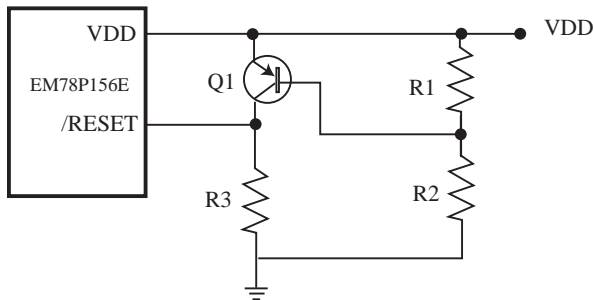Fig. 15   Circuit 1 for the residue voltage protection

Fig. 16   Circuit 2 for the residue voltage protection

VI.12 Instruction Set

Each instruction in the instruction set is a 13-bit word divided into an OP code and one or more operands. Normally, all instructions are executed within one single instruction cycle (one instruction consists of 2 oscillator periods), unless the program counter is changed by instruction "MOV R2,A", "ADD R2,A", or instructions of arithmetic or logic operation on R2 (e.g. "SUB R2,A", "BS(C) R2,6", "CLR R2", ...). In this case, the execution takes two instruction cycles.

Under some conditions, if the specification of the instruction cycle is not suitable for some applications, they can be modified as follows:

(A)   one instruction cycle consists of 4 oscillator periods.

(B)   "JMP", "CALL", "RET", "RETL", "RETI", and the conditional skip ("JBS", "JBC", "JZ", "JZA", "DJZ", "DJZA") tested to be true are executed within two instruction cycles. The instructions that write to the program counter also take two instruction cycles.

The Case (A) is selected by the CODE option bit, called CLKS. One instruction cycle consists of two oscillator clocks if CLKS is low, and consists of four oscillator clocks if CLKS is high.

Note that once 4 oscillator periods within one instruction cycle is selected in Case (A), the internal clock source to TCC is CLK=Fosc/4 instead of Fosc/ 2 that is shown in Fig.5.

In addition, the instruction set has the following features:

(1) Every bit of any register can be set, cleared or tested directly.

(2) The I/O registers can be regarded as general registers. That is, the same instruction can operate on I/O register.

The symbol "R" represents a register designator which specifies which one of the registers (including operational registers and general-purpose registers) to be utilized by the instruction. The symbol "b" represents a bit field designator which selects the number of the bit located in the register "R" affected by the operation. The symbol "k" represents an 8 or 10-bit constant or literal value.

Table 10   The list of the instruction set of EM78P156E

INSTRUCTION BINARY		HEX	MNEMONIC	OPERATION	STATUS AFFECTED
0	0000 0000 0000	0000	NOP	No Operation	None
0	0000 0000 0001	0001	DAA	Decimal Adjust A	C
0	0000 0000 0010	0002	CONTW	A → CONT	None
0	0000 0000 0011	0003	SLEP	0 → WDT, Stop oscillator	T,P
0	0000 0000 0100	0004	WDTC	0 → WDT	T,P
0	0000 0000 rrrr	000r	IOW R	A → IOCR	None <Note1>
0	0000 0001 0000	0010	ENI	Enable Interrupt	None
0	0000 0001 0001	0011	DISI	Disable Interrupt	None
0	0000 0001 0010	0012	RET	[Top of Stack] → PC	None
0	0000 0001 0011	0013	RETI	[Top of Stack] → PC, Enable Interrupt	None
0	0000 0001 0100	0014	CONTR	CONT → A	None
0	0000 0001 rrrr	001r	IOR R	IOCR → A	None <Note1>
0	0000 01rr rrrr	00rr	MOV R,A	A → R	None
0	0000 1000 0000	0080	CLRA	0 → A	Z
0	0000 11rr rrrr	00rr	CLR R	0 → R	Z
0	0001 00rr rrrr	01rr	SUB A,	R R-A → A	Z,C,DC
0	0001 01rr rrrr	01rr	SUB R,A	R-A → R	Z,C,DC
0	0001 10rr rrrr	01rr	DECA R	R-1 → A	Z
0	0001 11rr rrrr	01rr	DEC R	R-1 → R	Z
0	0010 00rr rrrr	02rr	OR A,R	A ∨ VR → A	Z
0	0010 01rr rrrr	02rr	OR R,A	A ∨ VR → R	Z
0	0010 10rr rrrr	02rr	AND A,R	A & R → A	Z
0	0010 11rr rrrr	02rr	AND R,A	A & R → R	Z
0	0011 00rr rrrr	03rr	XOR A,R	A ⊕ R → A	Z
0	0011 01rr rrrr	03rr	XOR R,A	A ⊕ R → R	Z
0	0011 10rr rrrr	03rr	ADD A,R	A + R → A	Z,C,DC
0	0011 11rr rrrr	03rr	ADD R,A	A + R → R	Z,C,DC
0	0100 00rr rrrr	04rr	MOV A,R	R → A	Z
0	0100 01rr rrrr	04rr	MOV R,R	R → R	Z
0	0100 10rr rrrr	04rr	COMA R	/R → A	Z
0	0100 11rr rrrr	04rr	COM R	/R → R	Z
0	0101 00rr rrrr	05rr	INCA R	R+1 → A	Z
0	0101 01rr rrrr	05rr	INC R	R+1 → R	Z
0	0101 10rr rrrr	05rr	DJZA	R R-1 → A, skip if zero	None
0	0101 11rr rrrr	05rr	DJZ R	R-1 → R, skip if zero	None
0	0110 00rr rrrr	06rr	RRCA R	R(n) → A(n-1) R(0) → C, C → A(7)	C
0	0110 01rr rrrr	06rr	RRC R	R(n) → R(n-1) R(0) → C, C → R(7)	C
0	0110 10rr rrrr	06rr	RLCA R	R(n) → A(n+1) R(7) → C, C → A(0)	C
0	0110 11rr rrrr	06rr	RLC R	R(n) → R(n+1) R(7) → C, C → R(0)	C
0	0111 00rr rrrr	07rr	SWAPA R	R(0-3) → A(4-7) R(4-7) → A(0-3)	None
0	0111 01rr rrrr	07rr	SWAP R	R(0-3) ↔ R(4-7)	None
0	0111 10rr rrrr	07rr	JZA R	R+1 → A, skip if zero	None
0	0111 11rr rrrr	07rr	JZ R	R+1 → R, skip if zero	None

INSTRUCTION BINARY	HEX	MNEMONIC	OPERATION	STATUS AFFECTED
0 100b bbrr rrrr	0xxx	BC R,b	0 → R(b)	None <Note2>
0 101b bbrr rrrr	0xxx	BS R,b	1 → R(b)	None <Note3>
0 110b bbrr rrrr	0xxx	JBC R,b	if R(b)=0, skip	None
0 111b bbrr rrrr	0xxx	JBS R,b	if R(b)=1, skip	None
1 00kk kkkk kkkk	1kkk	CALL k	PC+1 → [SP], (Page, k) → PC	None
1 01kk kkkk kkkk	1kkk	JMP k	(Page, k) → PC	None
1 1000 kkkk kkkk	18kk	MOV A,k	k → A	None
1 1001 kkkk kkkk	19kk	OR A,k	A ∨ k → A	Z
1 1010 kkkk kkkk	1Akk	AND A,k	A & k → A	Z
1 1011 kkkk kkkk	1Bkk	XOR A,k	A ⊕ k → A	Z
1 1100 kkkk kkkk	1Ckk	RETL k	k → A, [Top of Stack] → PC	None
1 1101 kkkk kkkk	1Dkk	SUB A,k	k-A → A	Z,C,DC
1 1110 0000 0001	1E01	INT	PC+1 → [SP], 001H → PC	None
1 1111 kkkk kkkk	1Fkk	ADD A,k	k+A → A	Z,C,DC

<Note 1> This instruction can operate on IOC5~IOC6, IOCA~IOCF only.

<Note 2> This instruction is not recommended to operate on RF.

<Note 3> This instruction cannot operate on RF.

VII. ABSOLUTE MAXIMUM RATINGS

Items	Sym.	Condition	Rating
Temperature under bias	T_{OPR}		0°C to 70°C
Storage temperature	T_{STR}		-65°C to 150°C
Input voltage	V_{IN}		-0.3V to +6.0V
Output voltage	V_O		-0.3V to +6.0V

VIII. DC ELECTRICAL CHARACTERISTIC (Ta=0°C ~ 70°C, V_{DD}=5.0V±5%, V_{SS}=0V)

Parameter	Sym.	Condition	Min.	Typ.	Max.	Unit
XTAL : VDD to 3V	Fxt	Two cycles with two clocks	DC		12.0	MHz
XTAL : VDD to 5V	Fxt		DC		18.0	MHz
ERC : VDD to 5V	F_{RC}	R : 5.1KΩ , C : 100pF	F±20%	760	F±20%	KHz
IRC : VDD to 5V	F_{RC}	R : 50KΩ	F±20%	4	F±20%	MHz
Input Leakage Current for input pins	I_{IL}	$V_{IN} = V_{DD}$, V_{SS}			±1	µA
Input High Voltage	V_{IH}	Ports 5, 6	2.0			V
Input Low Voltage	V_{IL}	Ports 5, 6			0.8	V
Input High Threshold Voltage	V_{IHT}	/RESET, TCC	2.0			V
Input Low Threshold Voltage	V_{ILT}	/RESET, TCC			0.8	V
Clock Input High Voltage	V_{IHX}	OSCI	3.5			V
Clock Input Low Voltage	V_{ILX}	OSCI			1.5	V
Output High Voltage (Port 5,6)	V_{OH1}	I_{OH} = -12mA	2.4			V
Output Low Voltage (P50~P53,P62~P67)	V_{OL1}	I_{OL} = 10.5mA			0.4	V
Output Low Voltage (P60,P61)	V_{OL2}	I_{OL} = 12mA			0.4	V
Pull-high current	I_{PH}	Pull-high active, input pin at V_{SS}	-50	-70	-240	µA
Pull-down current	I_{PD}	Pull-down active, input pin at V_{DD}	25	50	120	µA
Power-down current	I_{SB1}	All input and I/O pins at V_{DD}, output pin floating, WDT disabled			1	µA
Power-down current	I_{SB2}	All input and I/O pins at V_{DD}, output pin floating, WDT enabled			10	µA
Operating supply current (V_{DD}=3V) at two cycles/two clocks	I_{CC1}	/RESET='High', Fosc=32KHz(Crystal type, CLKS="0"), output pin floating, WDT disabled	15	15	30	µA
Operating supply current (V_{DD}=3V) at two cycles/two clocks	I_{CC2}	/RESET='High', Fosc=32KHz(Crystal type,CLKS="0"), output pin floating, WDT enabled		20	35	µA
Operating supply current (V_{DD}=5V) at two cycles/two clocks	I_{CC3}	/RESET='High', Fosc=4MHz (Crystal type,CLKS="0"), output pin floating WDT enable			1.6	mA
Operating supply current (V_{DD}=5V) at two cycles/two clocks	I_{CC4}	/RESET='High', Fosc=10MHz (Crystal type,CLKS="0"), output pin floating WDT enable			4	mA

IX. VOLTAGE DETECTOR ELECTRICAL CHARACTERISTIC (Ta = 25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Detect voltage	Vdet		1.7	1.8	1.9	V
Release voltage	Vrel			Vdet x1.05		V
Current consumption	Iss	V_{DD} = 5V			5	μA
Operating voltage	Vop		0.7*		5.5	V
Temperature characteristic of Vdet	ΔVdet/ ΔTa	0°C ≤Ta≤ 70°C			-2	mV/°C

X. AC ELECTRICAL CHARACTERISTICS (Ta=0°C ~ 70°C, V_{DD}=5.0V±5%, V_{SS}=0V)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input CLK duty cycle	Dclk		45	50	55	%
Instruction cycle time (CLKS="0")	Tins	XTAL Type	125		DC	ns
		RC Type	500		DC	ns
TCC input period	Ttcc		(Tins+20)/N*			ns
Device reset hold time	Tdrh	Ta = 25°C		16.8		ms
Watchdog Timer period	Twdt	Ta = 25°C		16.8		ms
Input pin setup time	Tset			0		ns
Input pin hold time	Thold			20		ns
Output pin delay time	Tdelay	Cload=20pF		50		ns

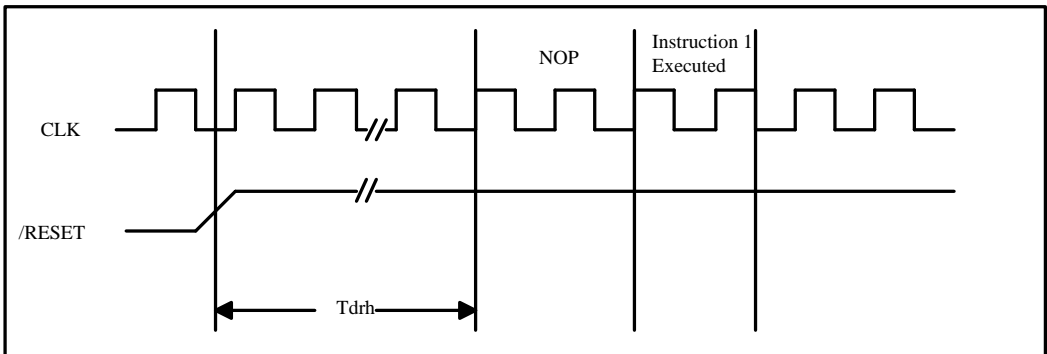Note : N*= selected prescaler ratio.

XI. TIMING DIAGRAMS

AC Test Input/Output Waveform
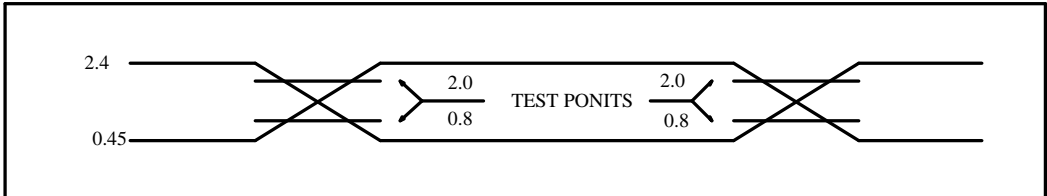
AC Testing : Input is driven at 2.4V for logic "1", and 0.45V for logic "0". Timing
measurements are made at 2.0V for logic "1", and 0.8V for logic "0".

RESET Timing (CLK="0")

TCC Input Timing (CLK="0")